



Fast Thyristor
Type TFI873-1600-40

Low switching losses
Low reverse recovery charge
Distributed amplified gate for high di_T/dt

Mean on-state current	I_{TAV}	1600 A
Repetitive peak off-state voltage	V_{DRM}	3800 ÷ 4000 V
Repetitive peak reverse voltage	V_{RRM}	
Turn-off time	t_q	125; 160 μs
V_{DRM}, V_{RRM}, V	3800	4000
Voltage code	38	40
$T_{ij}, ^\circ C$	- 60 ÷ 125	

MAXIMUM ALLOWABLE RATINGS

Symbols and parameters		Units	Values	Test conditions
ON-STATE				
I_{TAV}	Mean on-state current	A	1600 2600	$T_c=91\ ^\circ C$; Double side cooled; $T_c=55\ ^\circ C$; Double side cooled; 180° half-sine wave; 50 Hz
I_{TRMS}	RMS on-state current	A	2510	$T_c=91\ ^\circ C$; Double side cooled; 180° half-sine wave; 50 Hz
I_{TSM}	Surge on-state current	kA	32.0 37.0	180° half-sine wave; 50 Hz ($t_p=10\ ms$); single pulse; $V_D=V_R=0\ V$; Gate pulse: $I_G=I_{FGM}$; $V_G=20\ V$; $t_{GP}=50\ \mu s$; $di_G/dt=2\ A/\mu s$
			34.0 39.0	180° half-sine wave; 60 Hz ($t_p=8.3\ ms$); single pulse; $V_D=V_R=0\ V$; Gate pulse: $I_G=I_{FGM}$; $V_G=20\ V$; $t_{GP}=50\ \mu s$; $di_G/dt=2\ A/\mu s$
I^2t	Safety factor	$A^2s \cdot 10^3$	5120 6845	180° half-sine wave; 50 Hz ($t_p=10\ ms$); single pulse; $V_D=V_R=0\ V$; Gate pulse: $I_G=I_{FGM}$; $V_G=20\ V$; $t_{GP}=50\ \mu s$; $di_G/dt=2\ A/\mu s$
			4795 6310	180° half-sine wave; 60 Hz ($t_p=8.3\ ms$); single pulse; $V_D=V_R=0\ V$; Gate pulse: $I_G=I_{FGM}$; $V_G=20\ V$; $t_{GP}=50\ \mu s$; $di_G/dt=2\ A/\mu s$
BLOCKING				
V_{DRM}, V_{RRM}	Repetitive peak off-state and Repetitive peak reverse voltages	V	3800÷4000	$T_{j\ min} < T_j < T_{j\ max}$; 180° half-sine wave; 50 Hz; Gate open
V_{DSM}, V_{RSM}	Non-repetitive peak off-state and Non-repetitive peak reverse voltages	V	3900÷4100	$T_{j\ min} < T_j < T_{j\ max}$; 180° half-sine wave; 50 Hz; single pulse; Gate open
V_D, V_R	Direct off-state and Direct reverse voltages	V	0.75· V_{DRM} 0.75· V_{RRM}	$T_j=T_{j\ max}$; Gate open

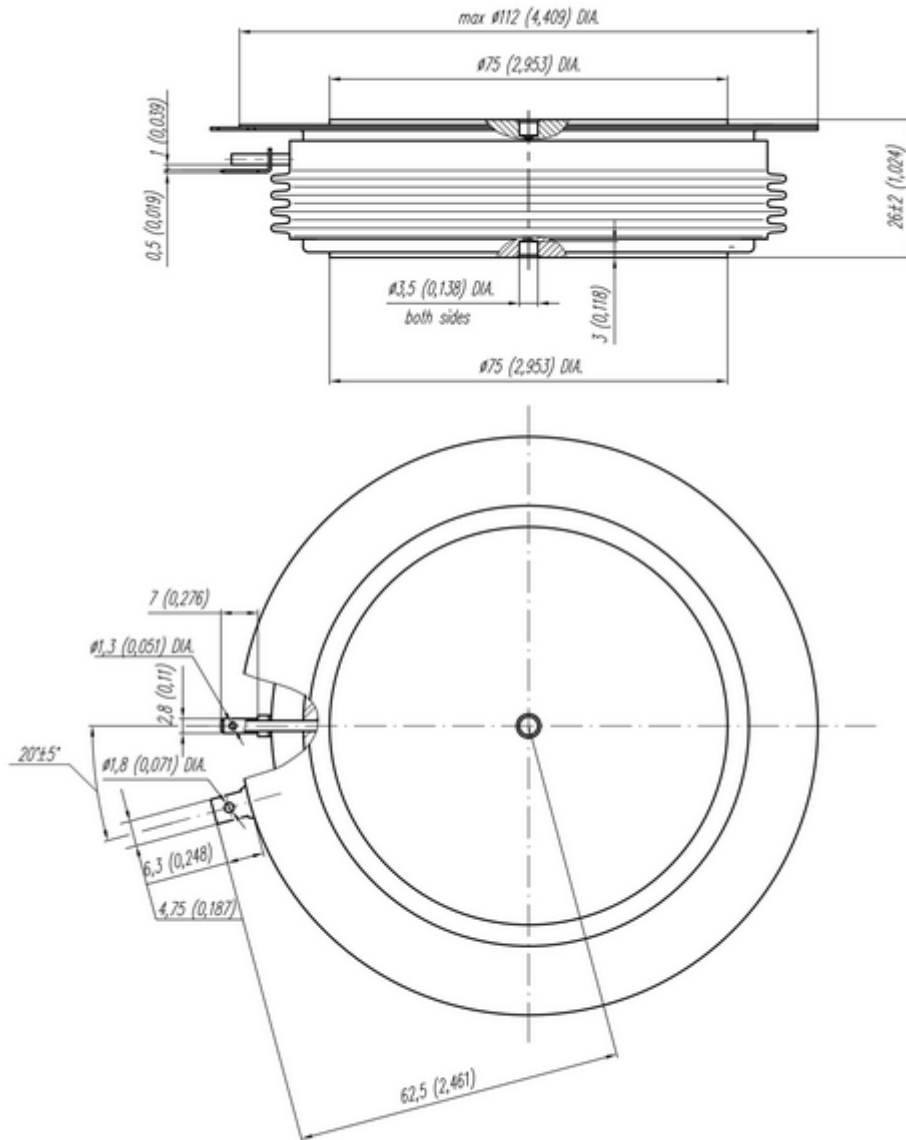
TRIGGERING				
I_{FGM}	Peak forward gate current	A	10	$T_j = T_{j\ max}$
V_{RGM}	Peak reverse gate voltage	V	5	
P_G	Gate power dissipation	W	8	$T_j = T_{j\ max}$ for DC gate current
SWITCHING				
$(di_T/dt)_{crit}$	Critical rate of rise of on-state current non-repetitive (f=1 Hz)	A/ μ s	2000	$T_j = T_{j\ max}$; $V_D = 0.67 \cdot V_{DRM}$; $I_{TM} = 2 I_{TAV}$; Gate pulse: $I_G = I_{FGM}$; $V_G = 20$ V; $t_{GP} = 50$ μ s; $di_G/dt = 2$ A/ μ s
THERMAL				
T_{stg}	Storage temperature	$^{\circ}$ C	-60 \div 125	
T_j	Operating junction temperature	$^{\circ}$ C	-60 \div 125	
MECHANICAL				
F	Mounting force	kN	40.0 \div 50.0	
a	Acceleration	m/s ²	50 100	Device unclamped Device clamped

CHARACTERISTICS

Symbols and parameters		Units	Values	Conditions	
ON-STATE					
V_{TM}	Peak on-state voltage, max	V	2.40 2.70	$T_j = T_{j\ max}$; $I_{TM} = 4000$ A $T_j = 25$ $^{\circ}$ C; $I_{TM} = 5024$ A	
$V_{T(TO)}$	On-state threshold voltage, max	V	1.44	$T_j = T_{j\ max}$;	
r_T	On-state slope resistance, max	m Ω	0.270	$0.5 \pi I_{TAV} < I_T < 1.5 \pi I_{TAV}$	
I_H	Holding current, max	mA	1000	$T_j = 25$ $^{\circ}$ C; $V_D = 12$ V; Gate open	
BLOCKING					
I_{DRM} , I_{RRM}	Repetitive peak off-state and Repetitive peak reverse currents, max	mA	300	$T_j = T_{j\ max}$; $V_D = V_{DRM}$; $V_R = V_{RRM}$	
$(dv_D/dt)_{crit}$	Critical rate of rise of off-state voltage ¹⁾ , min	V/ μ s	1000	$T_j = T_{j\ max}$; $V_D = 0.67 \cdot V_{DRM}$; Gate open	
TRIGGERING					
V_{GT}	Gate trigger direct voltage, max	V	5.00 3.00 2.00	$T_j = T_{j\ min}$ $T_j = 25$ $^{\circ}$ C $T_j = T_{j\ max}$	$V_D = 12$ V; $I_D = 3$ A; Direct gate current
I_{GT}	Gate trigger direct current, max	mA	500 300 200	$T_j = T_{j\ min}$ $T_j = 25$ $^{\circ}$ C $T_j = T_{j\ max}$	
V_{GD}	Gate non-trigger direct voltage, min	V	0.35	$T_j = T_{j\ max}$; $V_D = 0.67 \cdot V_{DRM}$;	
I_{GD}	Gate non-trigger direct current, min	mA	15.00	Direct gate current	
SWITCHING					
t_{gd}	Delay time	μ s	3.5	$T_j = 25$ $^{\circ}$ C; $V_D = 0.4 \cdot V_{DRM}$; $I_{TM} = I_{TAV}$; Gate pulse: $I_G = I_{FGM}$; $V_G = 20$ V; $t_{GP} = 50$ μ s; $di_G/dt = 2$ A/ μ s	
t_q	Turn-off time ²⁾ , max	μ s	125; 160	$dv_D/dt = 50$ V/ μ s;	$T_j = T_{j\ max}$; $I_{TM} = I_{TAV}$; $di_r/dt = -10$ A/ μ s; $V_R = 100$ V; $V_D = 0.67 V_{DRM}$
			160; 200	$dv_D/dt = 200$ V/ μ s;	
Q_{rr}	Total recovered charge(linear), max	μ C	3000	$T_j = T_{j\ max}$; $I_{TM} = 2000$ A;	
t_{rr}	Reverse recovery time, max	μ s	14	$di_r/dt = -50$ A/ μ s;	
I_{rrM}	Peak reverse recovery current, max	A	430	$V_R = 100$ V	

THERMAL					
R_{thjc}	Thermal resistance, junction to case, max	°C/W	0.0085	Direct current	Double side cooled
R_{thjc-A}			0.0187		Anode side cooled
R_{thjc-K}			0.0153		Cathode side cooled
R_{thck}	Thermal resistance, case to heatsink, max	°C/W	0.0020	Direct current	
MECHANICAL					
w	Weight, typ	g	1500		
D_s	Surface creepage distance	mm (inch)	36.6 (1.441)		
D_a	Air strike distance	mm (inch)	16.2 (0.638)		

NOTES		PART NUMBERING GUIDE																												
¹⁾ Critical rate of rise of off-state voltage <table border="1"> <tr> <td>Symbol of group</td> <td colspan="2">A2</td> </tr> <tr> <td>$(dv_D/dt)_{crit}$, V/μs</td> <td colspan="2">1000</td> </tr> </table>		Symbol of group	A2		$(dv_D/dt)_{crit}$, V/μs	1000		<table border="1"> <tr> <td>TFI</td> <td>873</td> <td>1600</td> <td>40</td> <td>A2</td> <td>X2</td> <td colspan="2">N</td> </tr> <tr> <td>1</td> <td>2</td> <td>3</td> <td>4</td> <td>5</td> <td>6</td> <td colspan="2">7</td> </tr> </table>							TFI	873	1600	40	A2	X2	N		1	2	3	4	5	6	7	
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²⁾ Turn-off time ($dv_D/dt=50$ V/μs) <table border="1"> <tr> <td>Symbol of group</td> <td>X2</td> <td>T2</td> </tr> <tr> <td>t_{qr}, μs</td> <td>125</td> <td>160</td> </tr> </table>		Symbol of group	X2	T2	t_{qr} , μs	125	160	<ol style="list-style-type: none"> TFI — Fast Thyristor TFIS — Fast Thyristor with Distributed Amplified Gate Design version Mean on-state current, A Voltage code Critical rate of rise of off-state voltage Group of turn-off time ($dv_D/dt=50$ V/μs) Ambient conditions: N – normal; T – tropical 																						
Symbol of group	X2	T2																												
t_{qr} , μs	125	160																												



All dimensions in millimeters (inches)

On-state characteristic model (see Fig. 1).

Analytical function for On-state characteristic:

$$V_T = A + B \cdot i_T + C \cdot \ln(i_T + 1) + D \cdot \sqrt{i_T}$$

	Coefficients	
	T _j = 25°C	T _j = T _{j max}
A	1.799223	1.165741
B	0.106392	0.195115
C	-0.227901	-0.304378
D	0.350140	0.467637

Transient thermal impedance junction to case Z_{thjc} model (see Fig. 2).

Analytical function for Transient thermal impedance junction to case Z_{thjc} for DC:

$$Z_{thjc} = \sum_{i=1}^n R_i \left(1 - e^{-\frac{t}{\tau_i}} \right)$$

Where *i* = 1 to *n*, *n* is the number of terms in the series.

t = Duration of heating pulse in seconds.

Z_{thjc} = Thermal resistance at time *t*.

R_i = Amplitude of p_{th} term.

τ_i = Time constant of r_{th} term.

DC Double side cooled

i	1	2	3	4	5	6
R_i, K/W	0.00007989	0.002973	0.0005936	0.000846	0.00005975	0.003948
τ_i, s	1.688	0.06219	0.002329	0.138	0.0003243	0.9533

DC Anode side cooled

i	1	2	3	4	5	6
R_i, K/W	0.01013	0.004062	0.0009401	0.002853	0.0005963	0.00005641
τ_i, s	9.747	1.058	0.1304	0.06179	0.002313	0.0003013

DC Cathode side cooled

i	1	2	3	4	5	6
R_i, K/W	0.006619	0.004034	0.0008595	0.002956	0.0005965	0.00005689
τ_i, s	9.744	1.025	0.1394	0.06237	0.002318	0.0003037

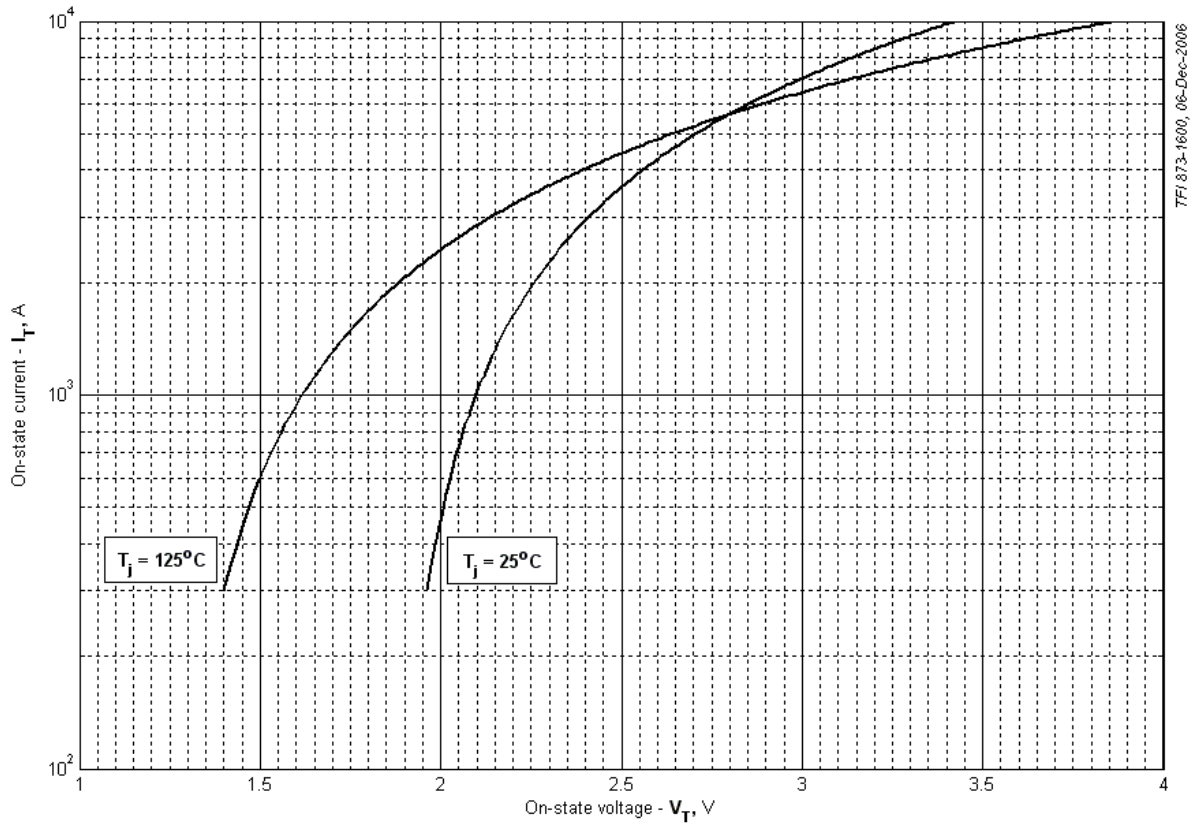


Fig 1 – On-state characteristics of Limit device

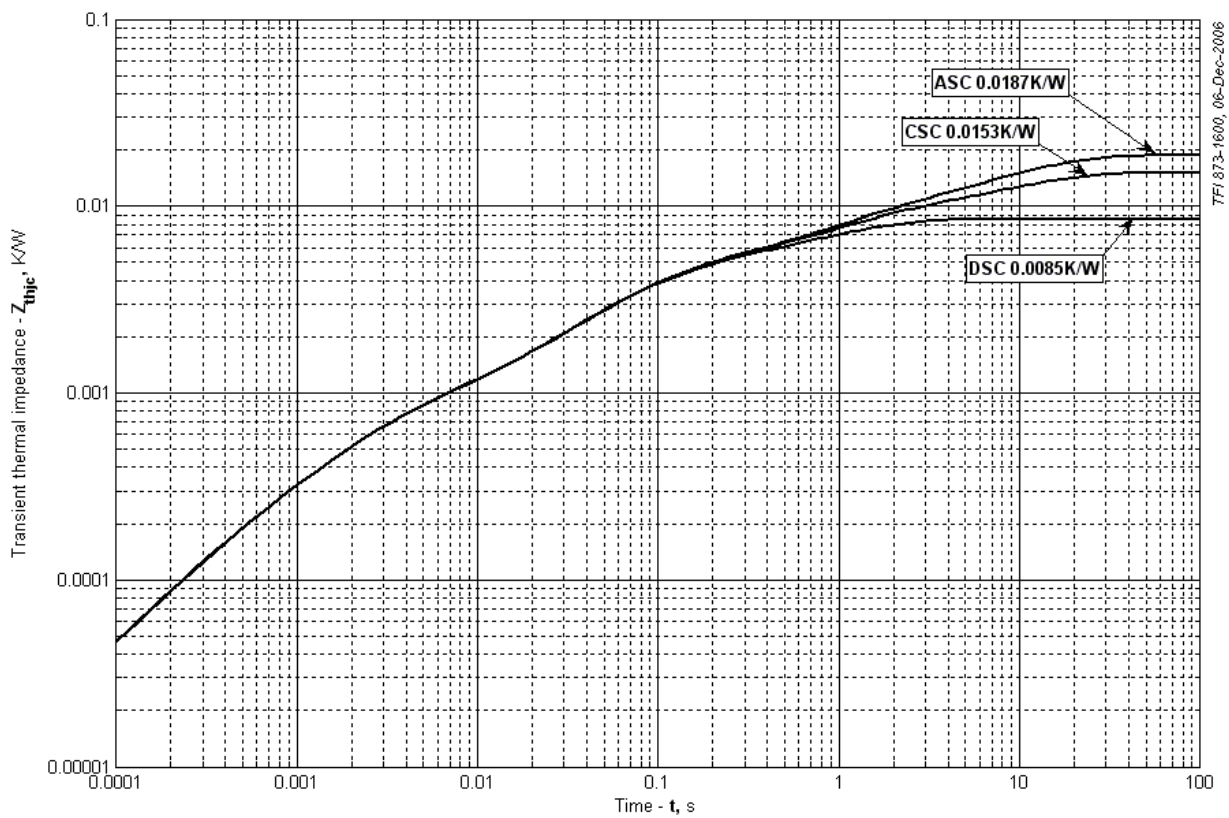


Fig 2 – Transient thermal impedance

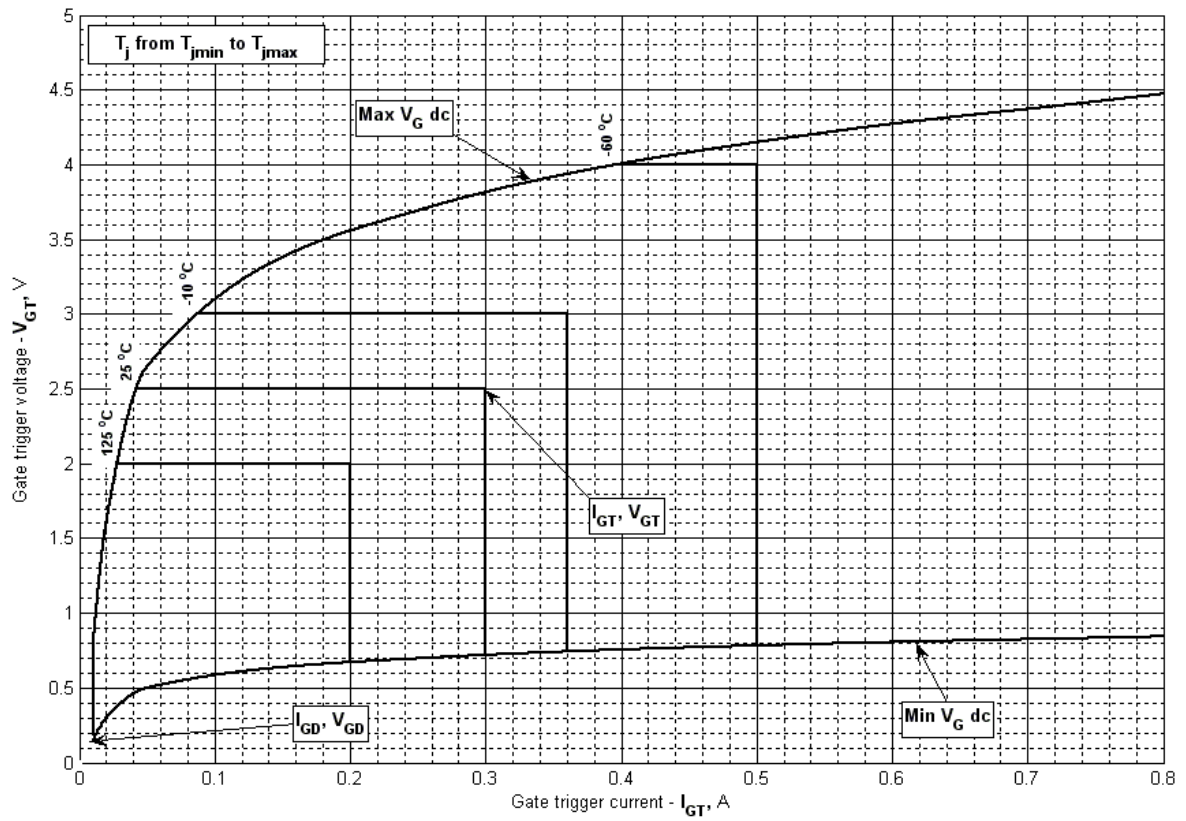


Fig 3 – Gate characteristics – Trigger limits

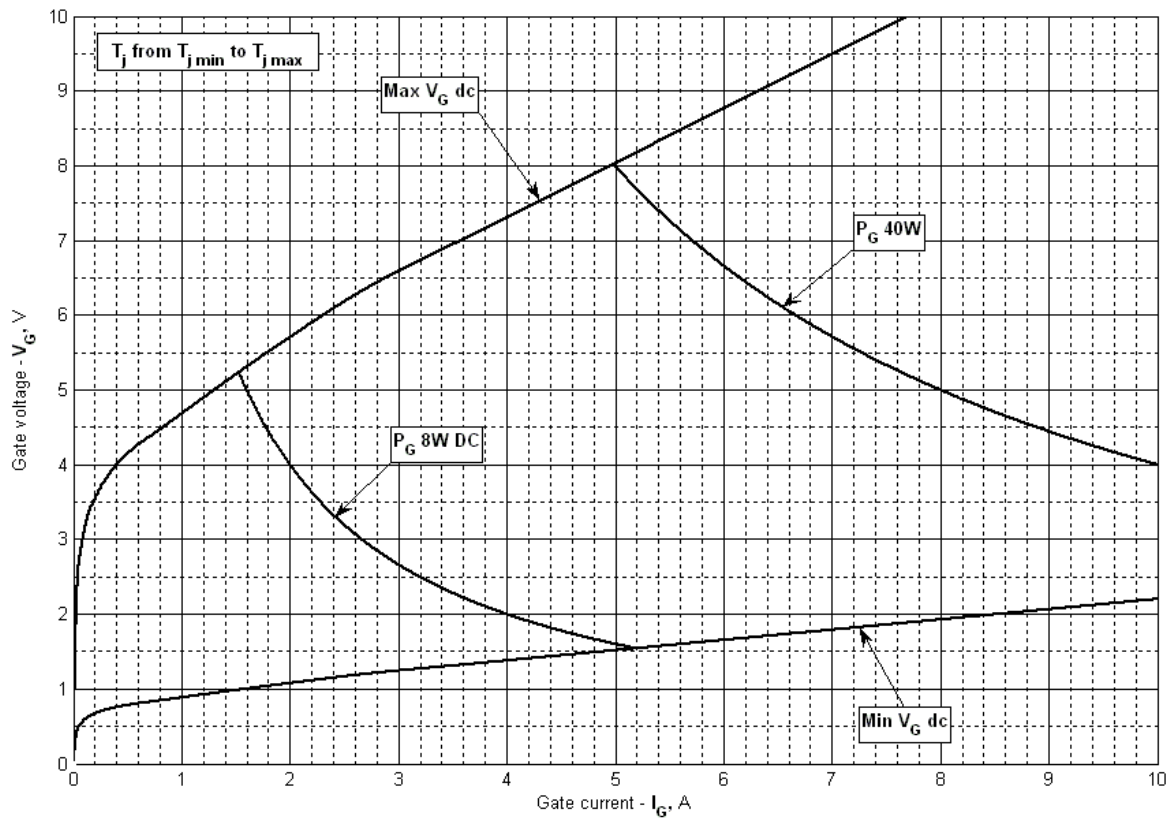


Fig 4 - Gate characteristics –Power curves

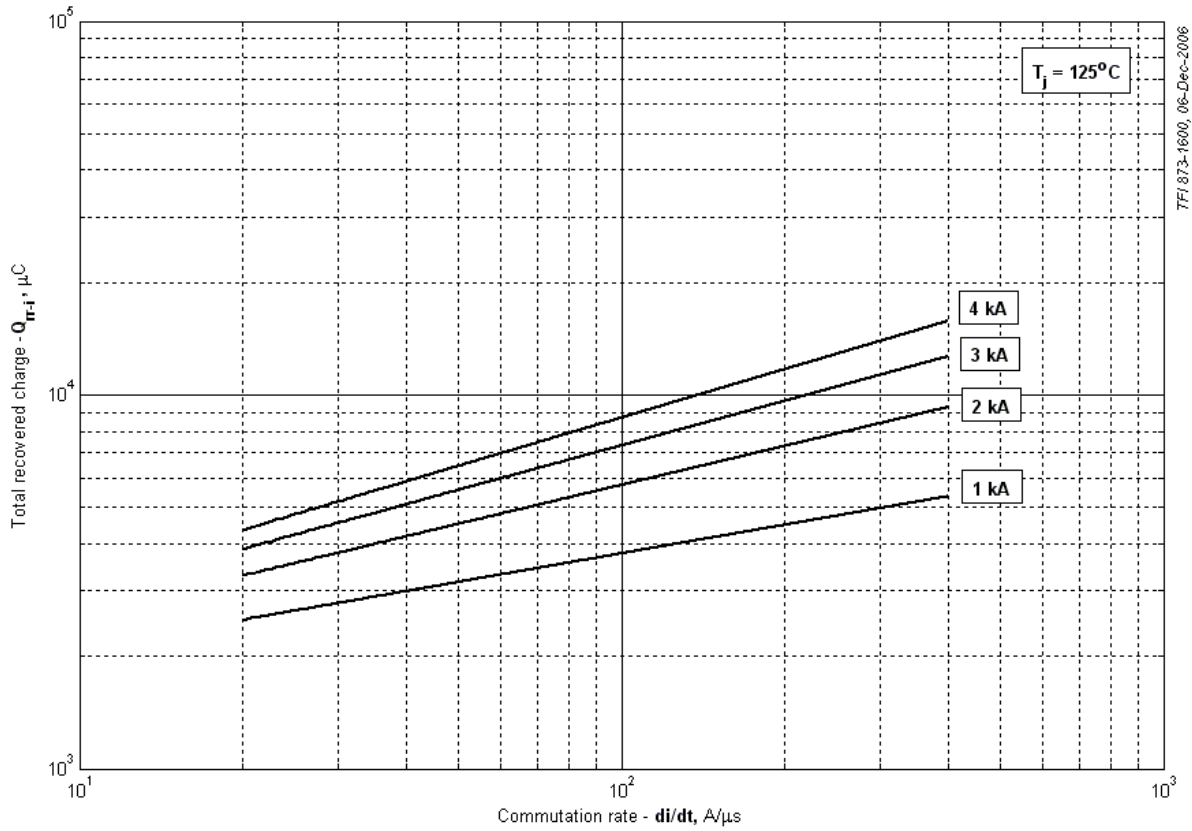


Fig 5 – Total recovered charge, Q_{tr-i} (integral)

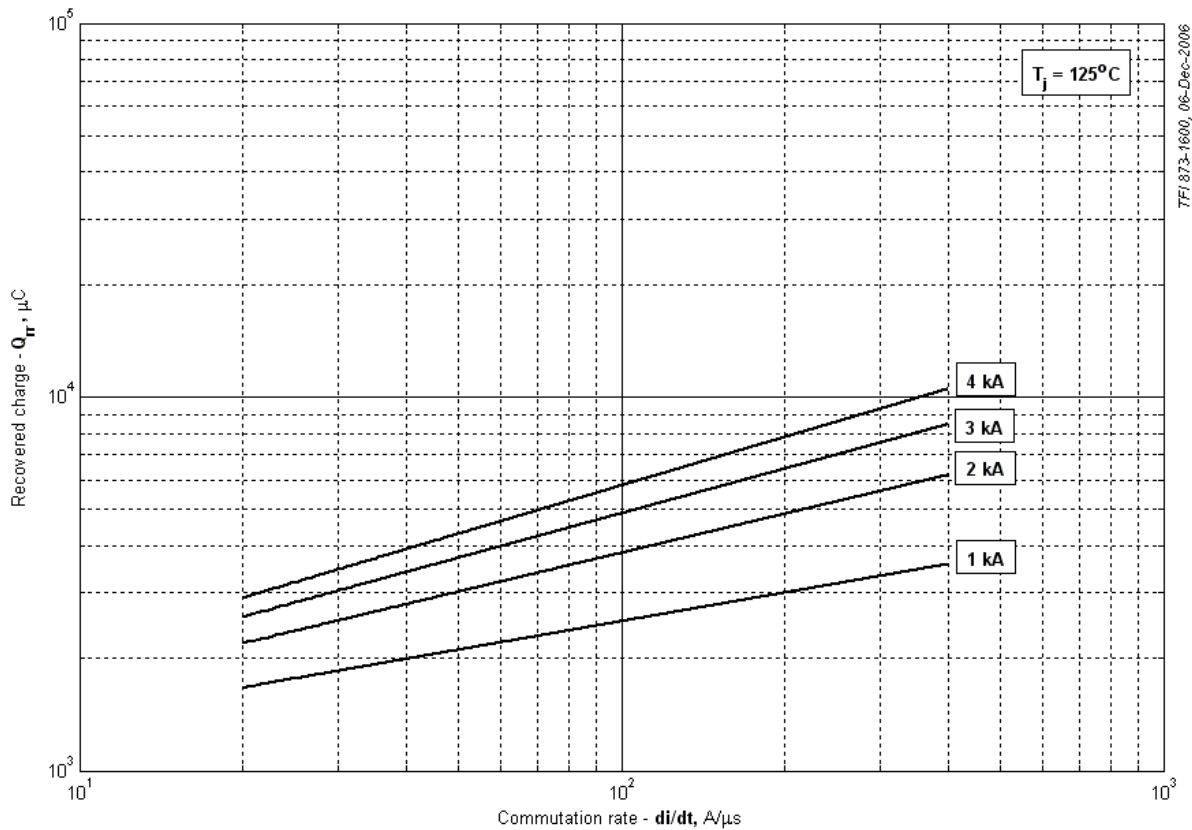


Fig 6 - Recovered charge, Q_{tr} (linear)

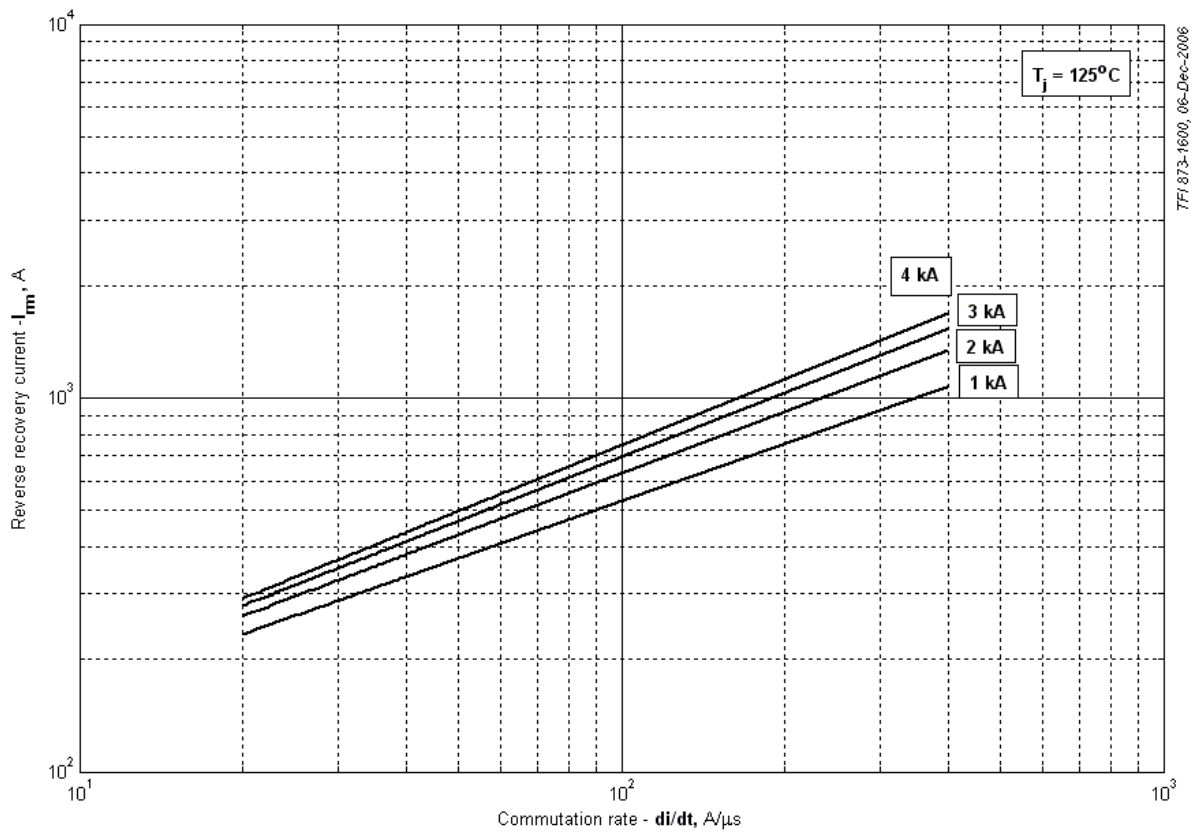


Fig 7 – Peak reverse recovery current, I_{rm}

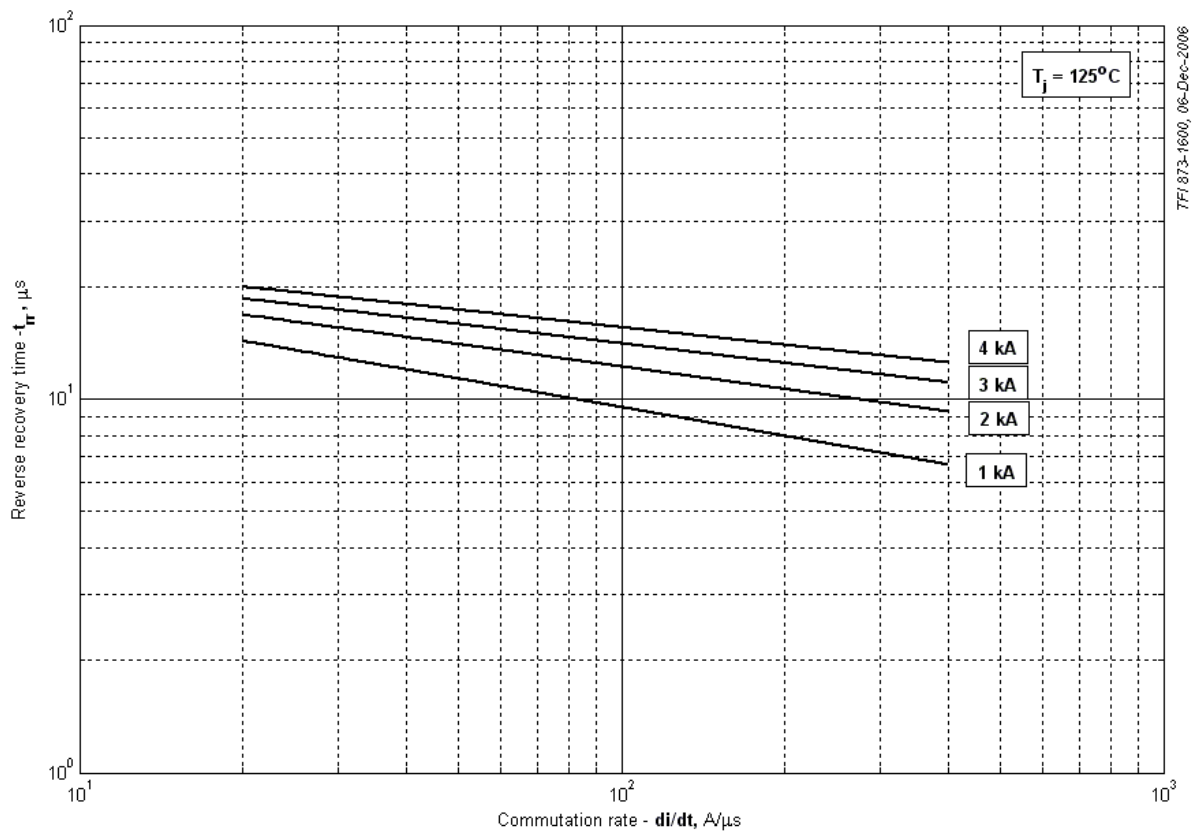


Fig 8 – Maximum recovery time, t_{tr} (linear)

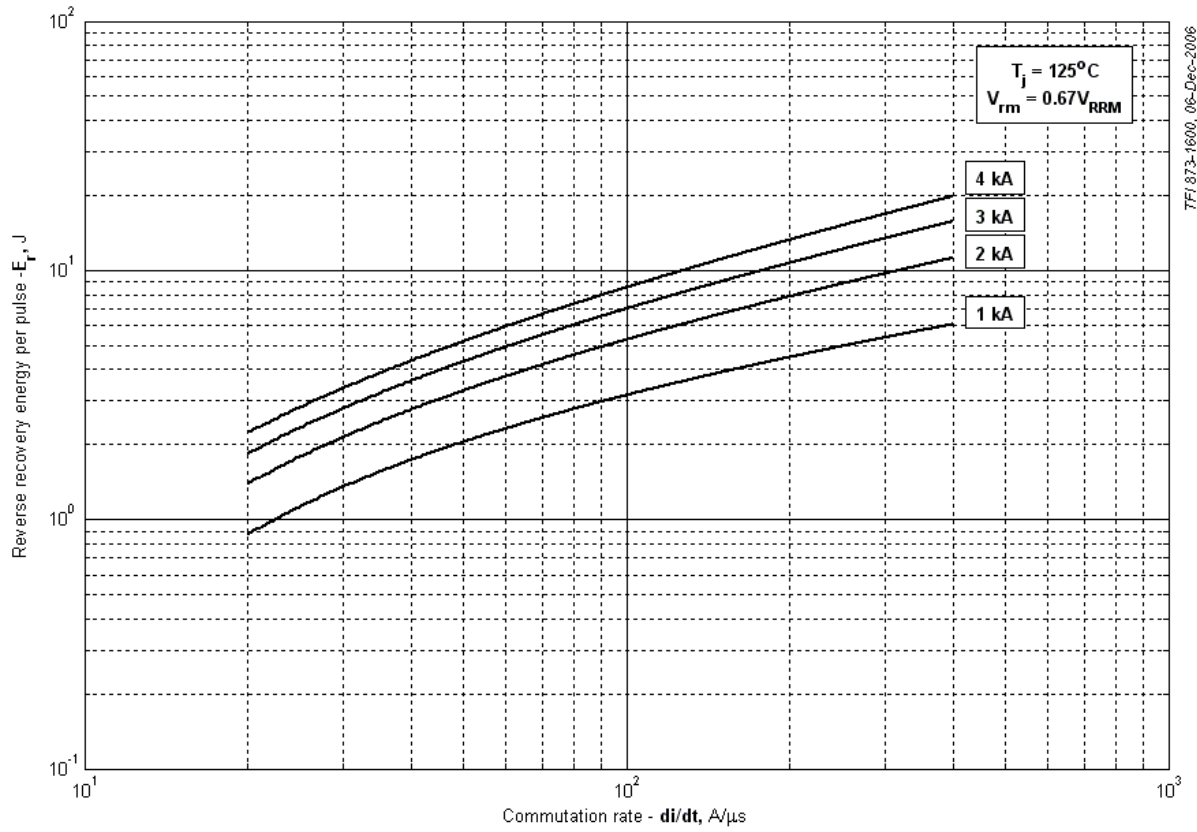


Fig 9 – Reverse recovery energy per pulse

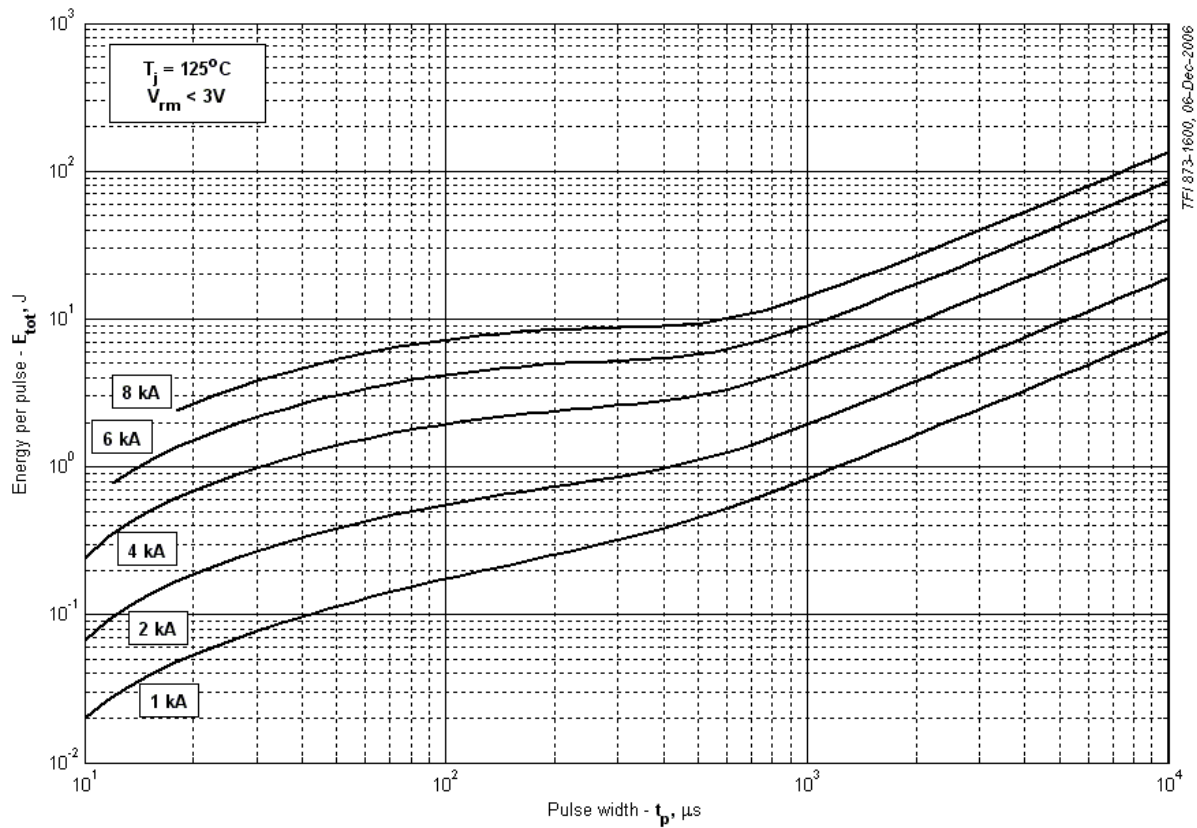


Fig 10 – Sine wave energy per pulse

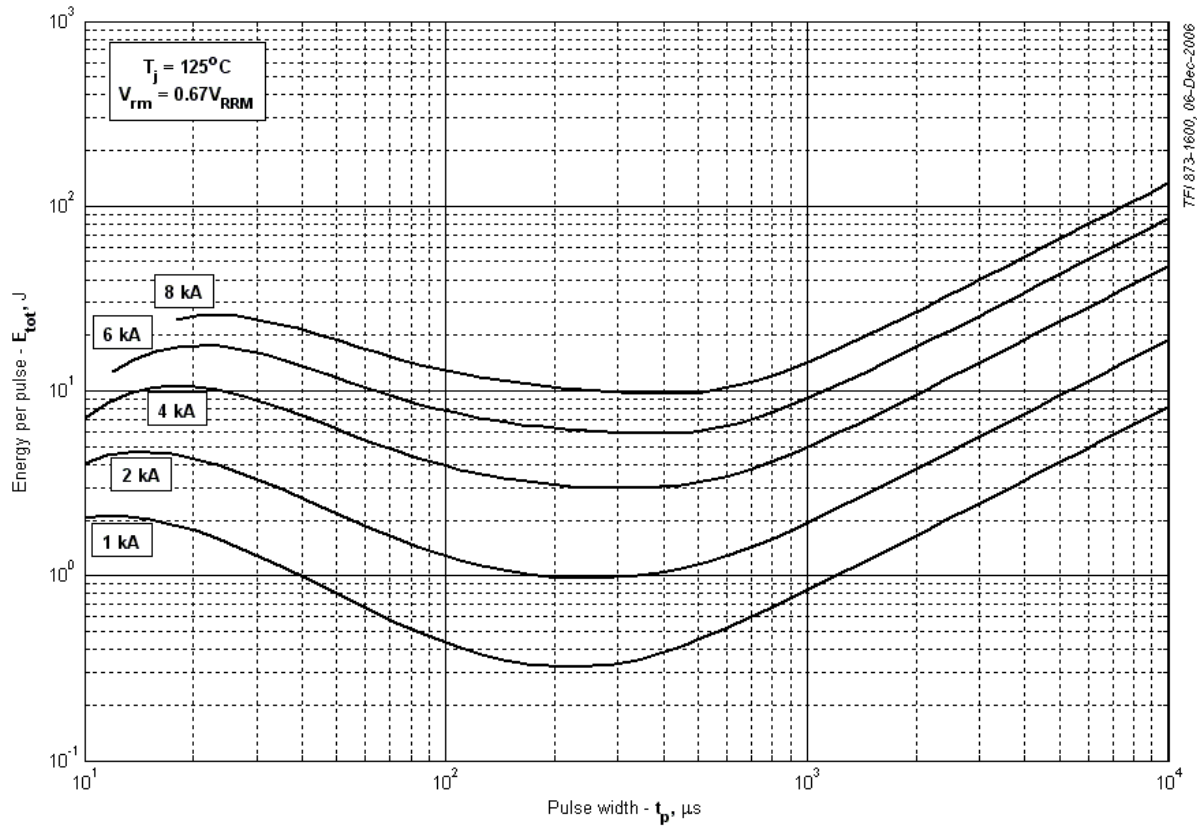


Fig 11 – Sine wave energy per pulse

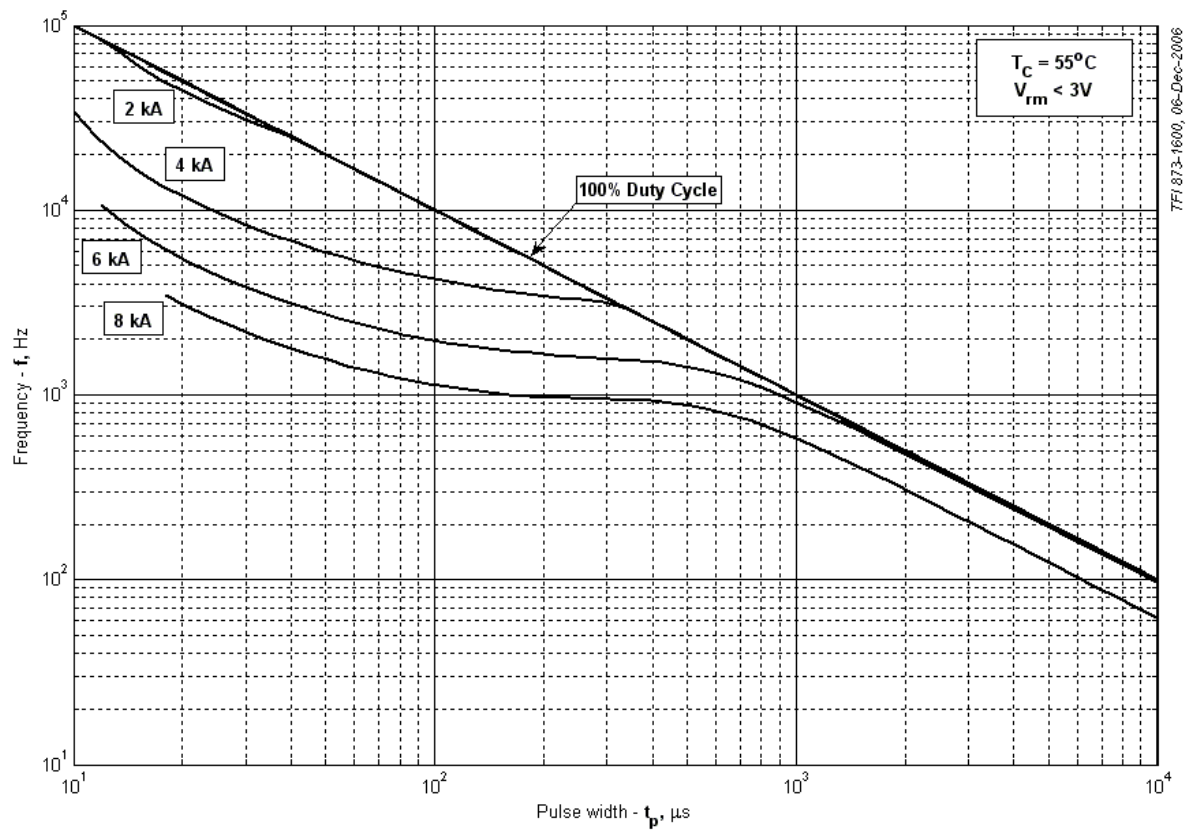
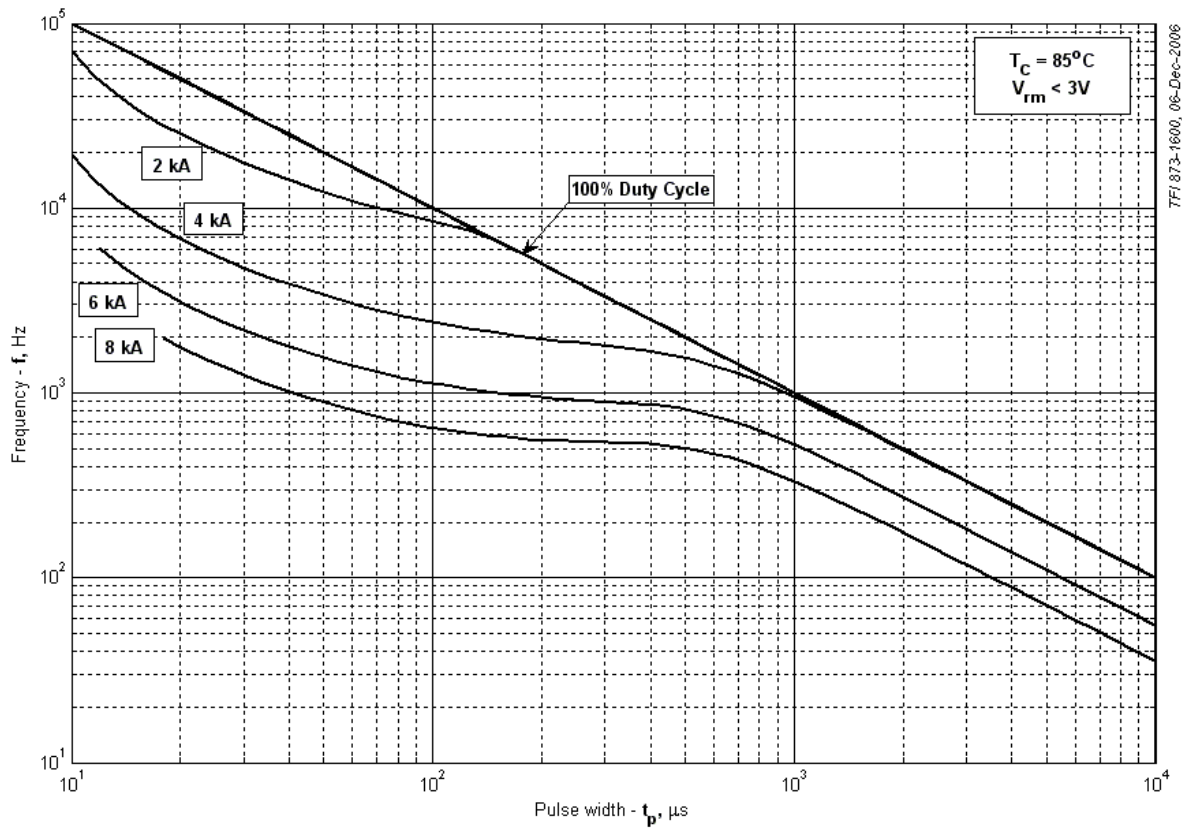
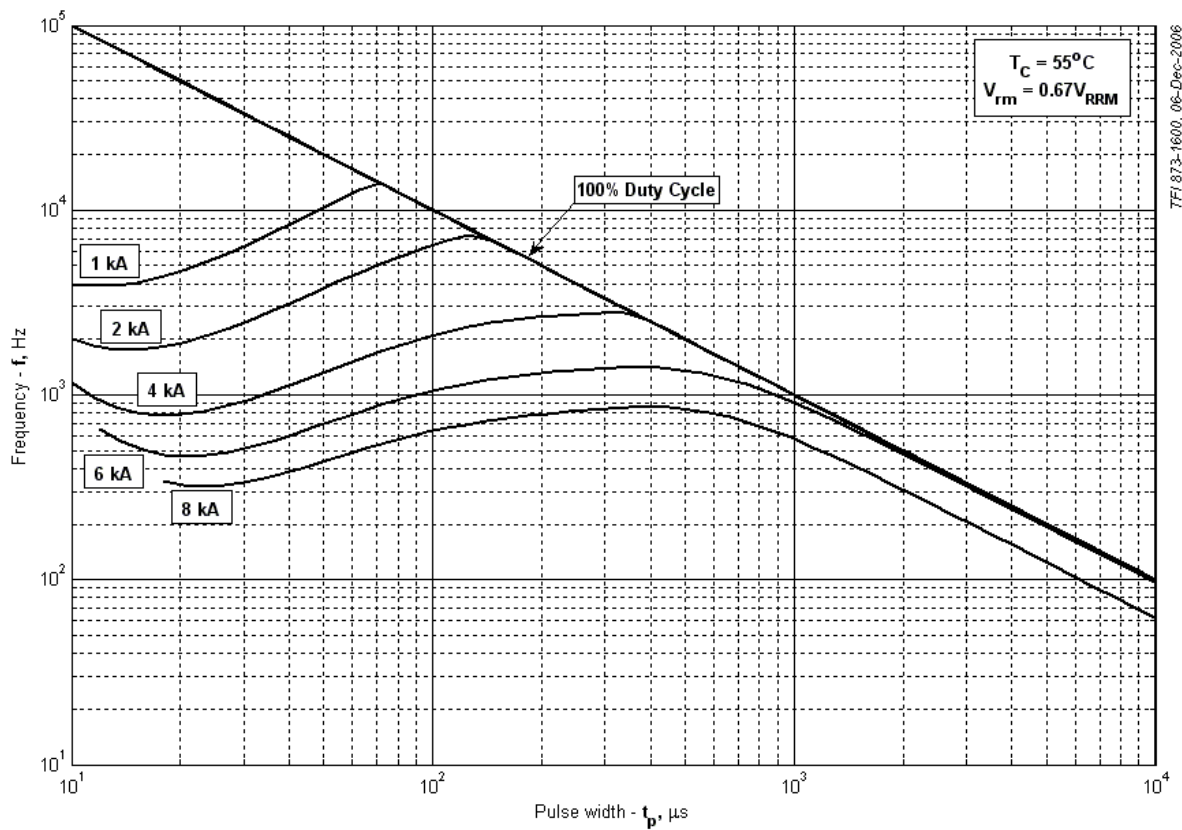


Fig 12 – Sine wave frequency ratings



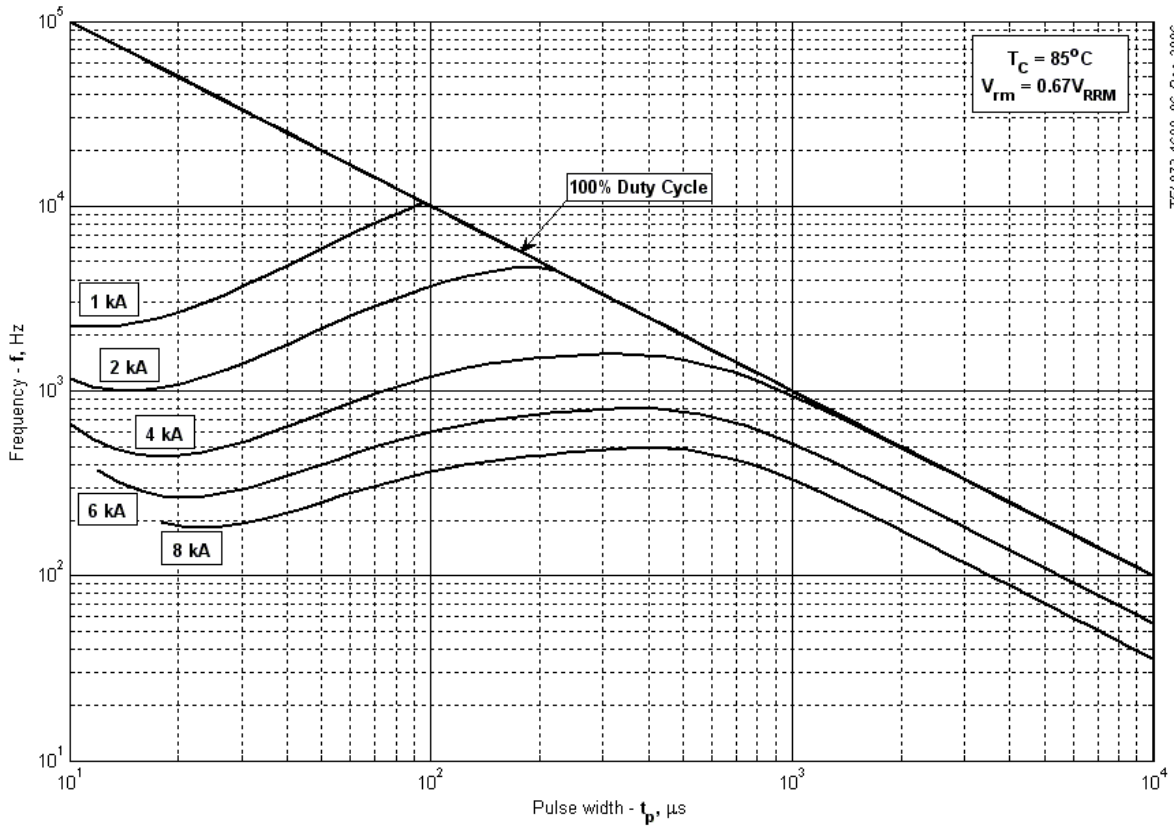
TFI873-1600, 06-Dec-2006

Fig 13 – Sine wave frequency ratings



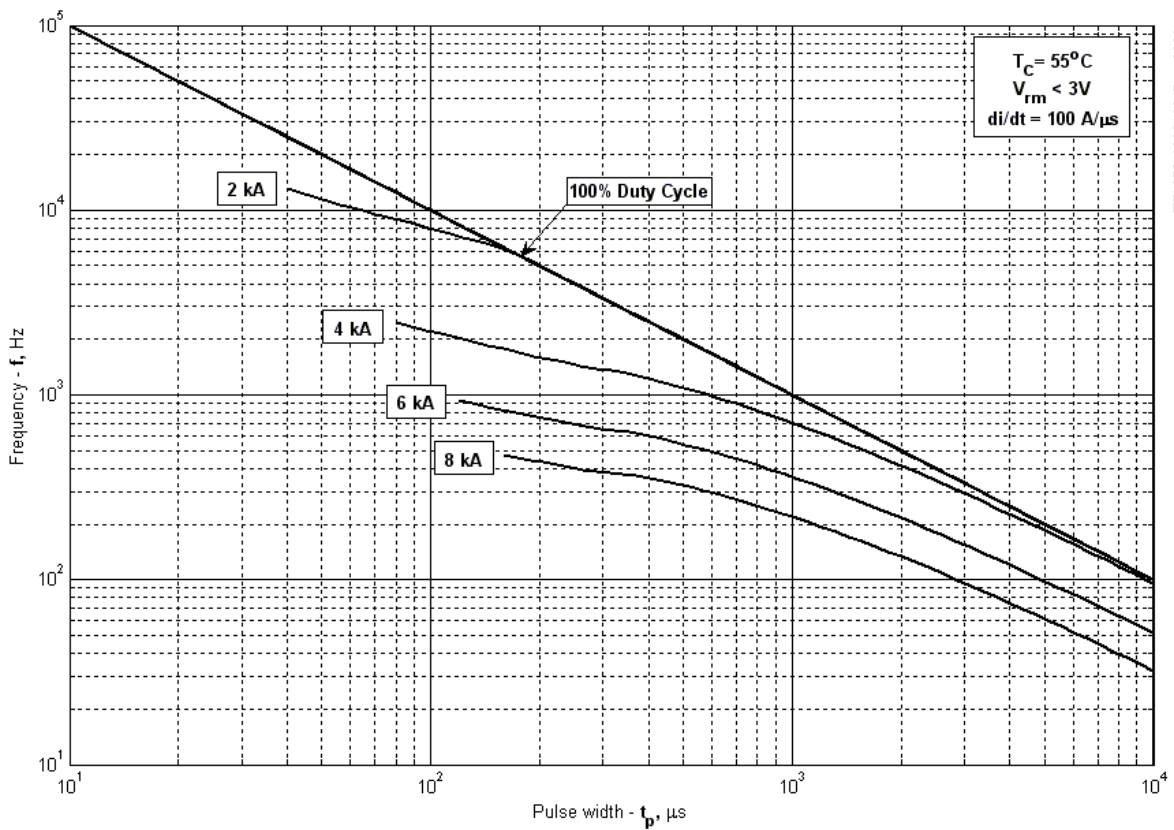
TFI873-1600, 06-Dec-2006

Fig 14 – Sine wave frequency ratings



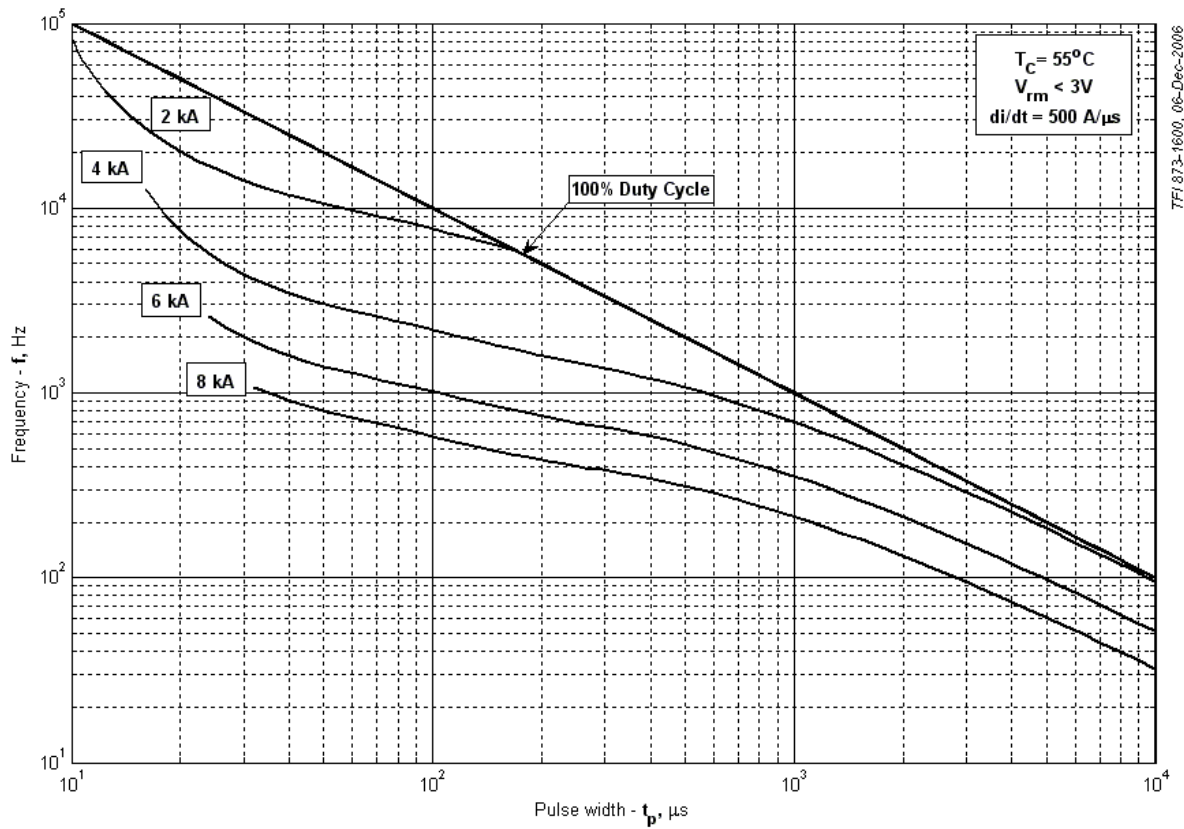
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Fig 15 – Sine wave frequency ratings



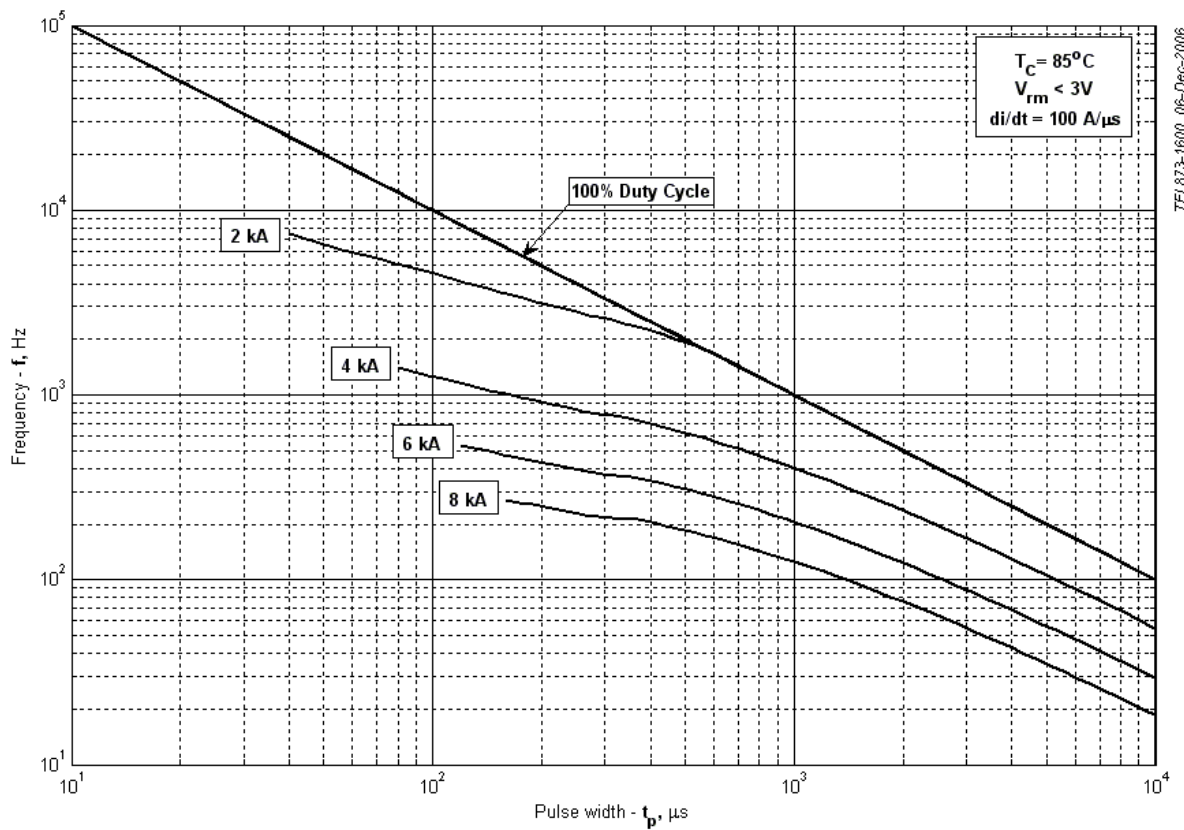
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Fig 16 – Square wave frequency ratings



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Fig 17 – Square wave frequency ratings



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Fig 18 – Square wave frequency ratings

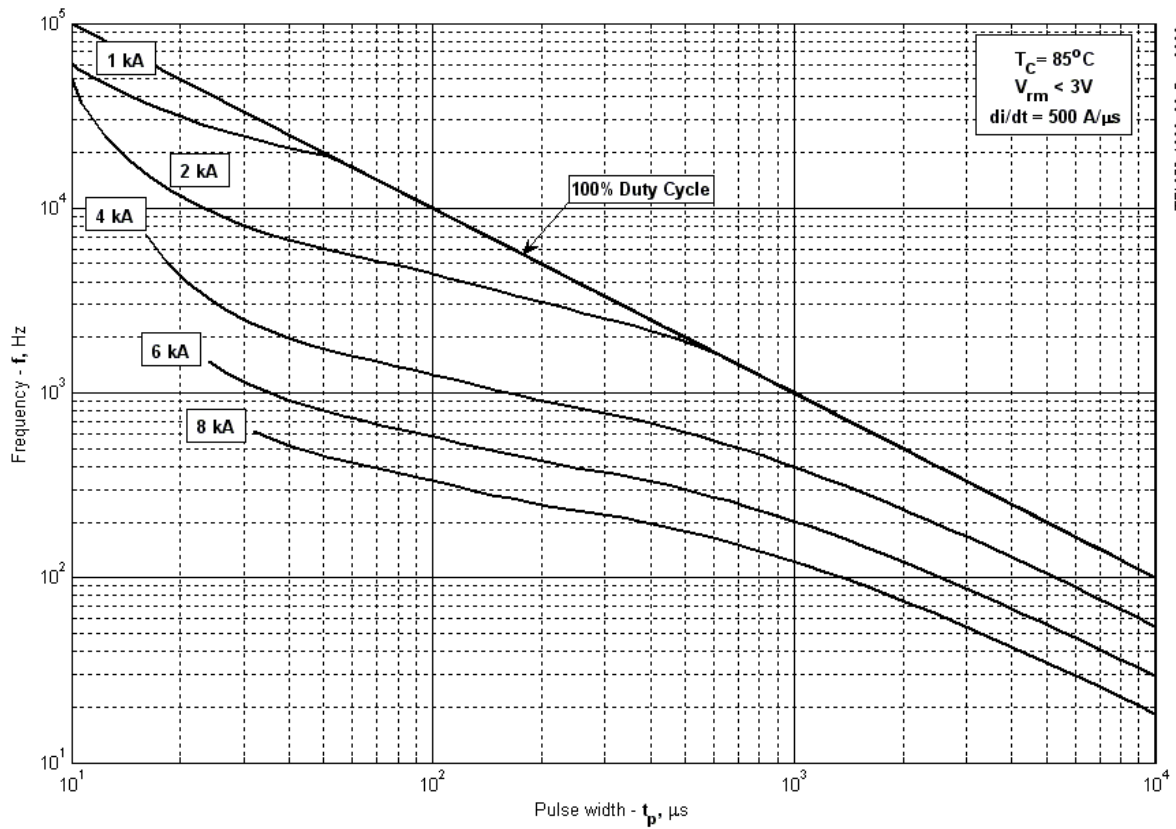


Fig 19 – Square wave frequency ratings

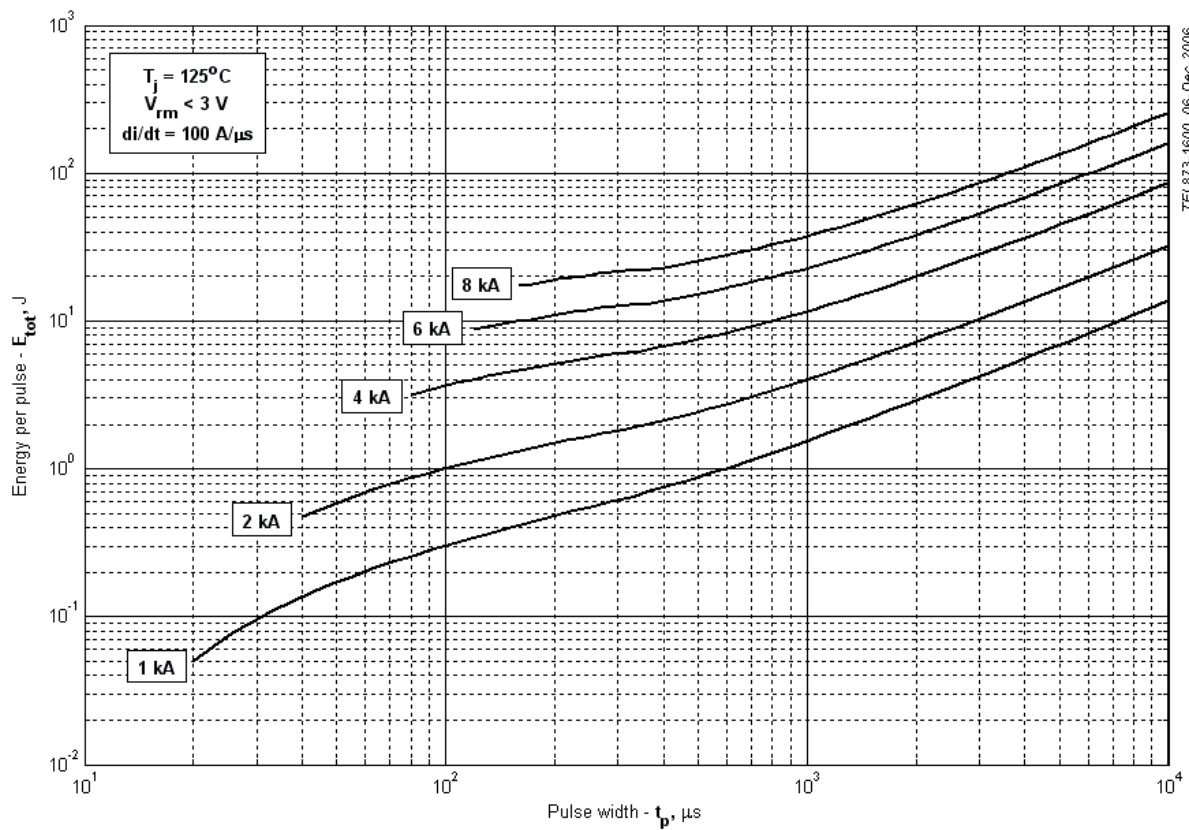
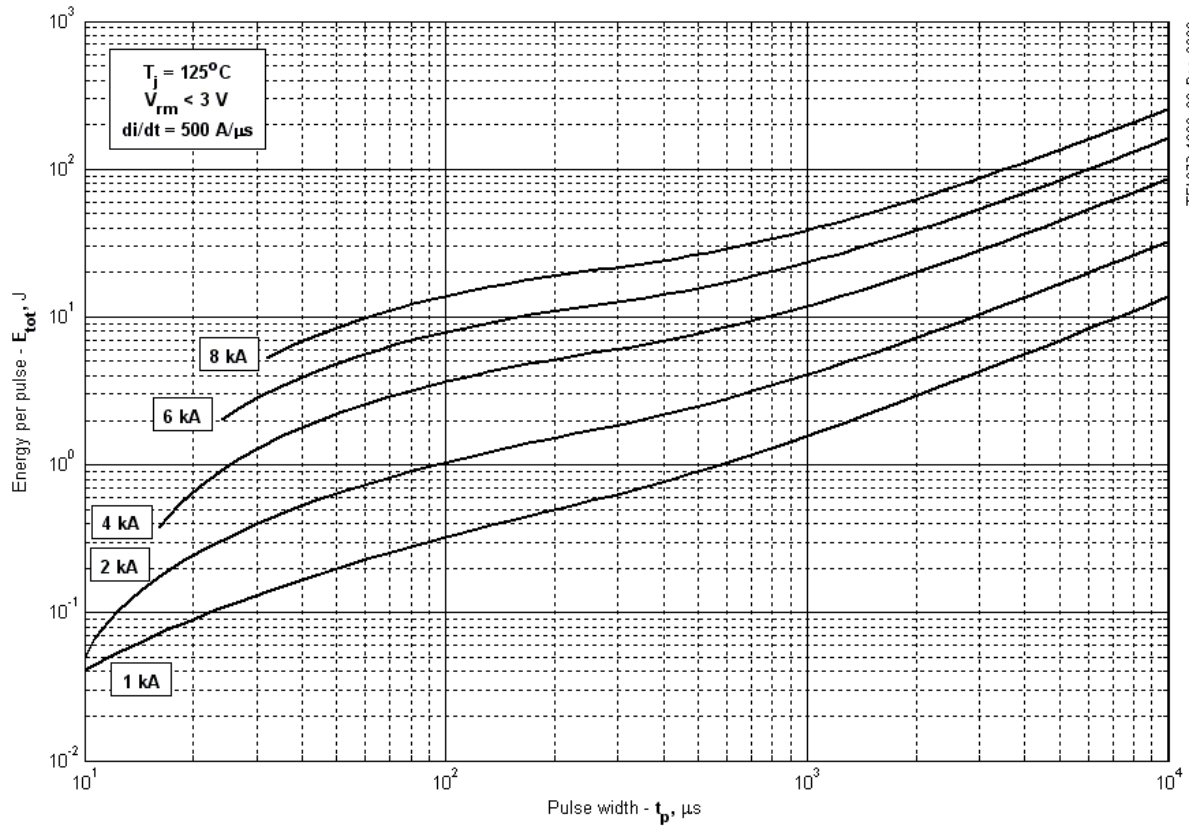
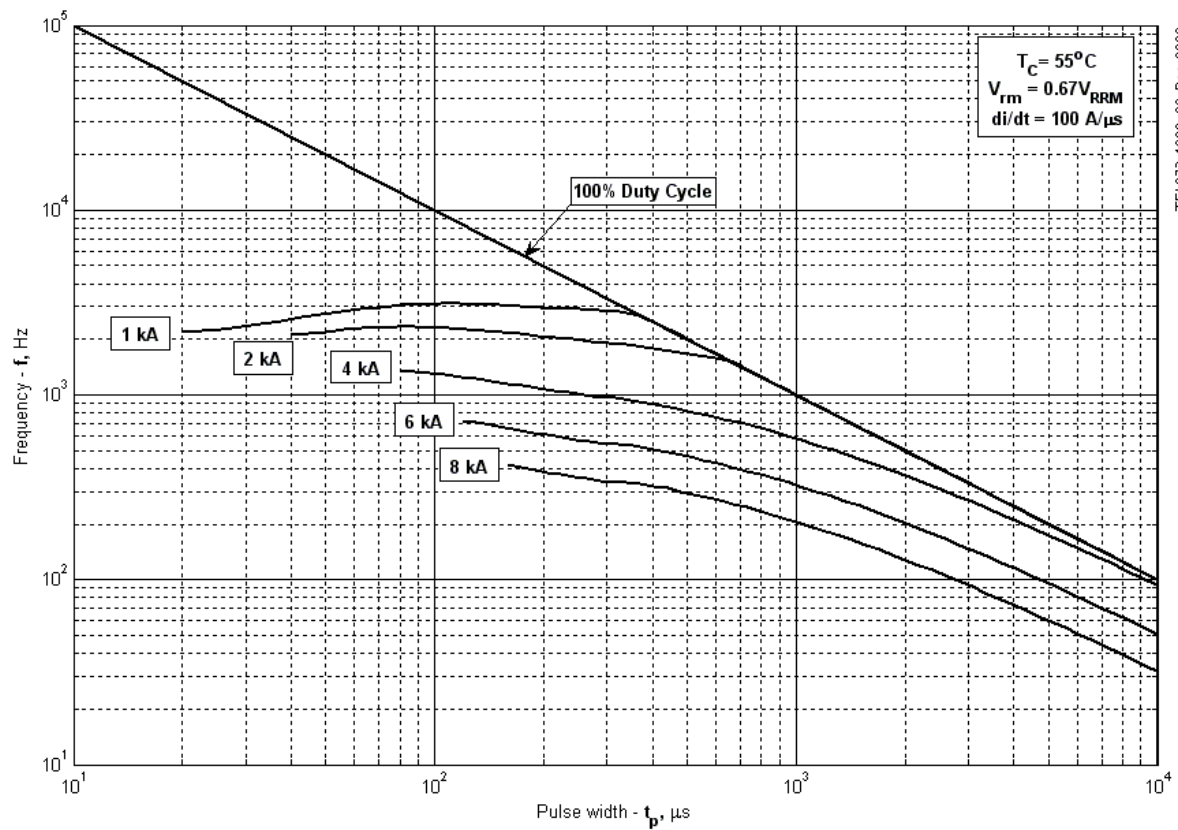


Fig 20 – Square wave energy per pulse



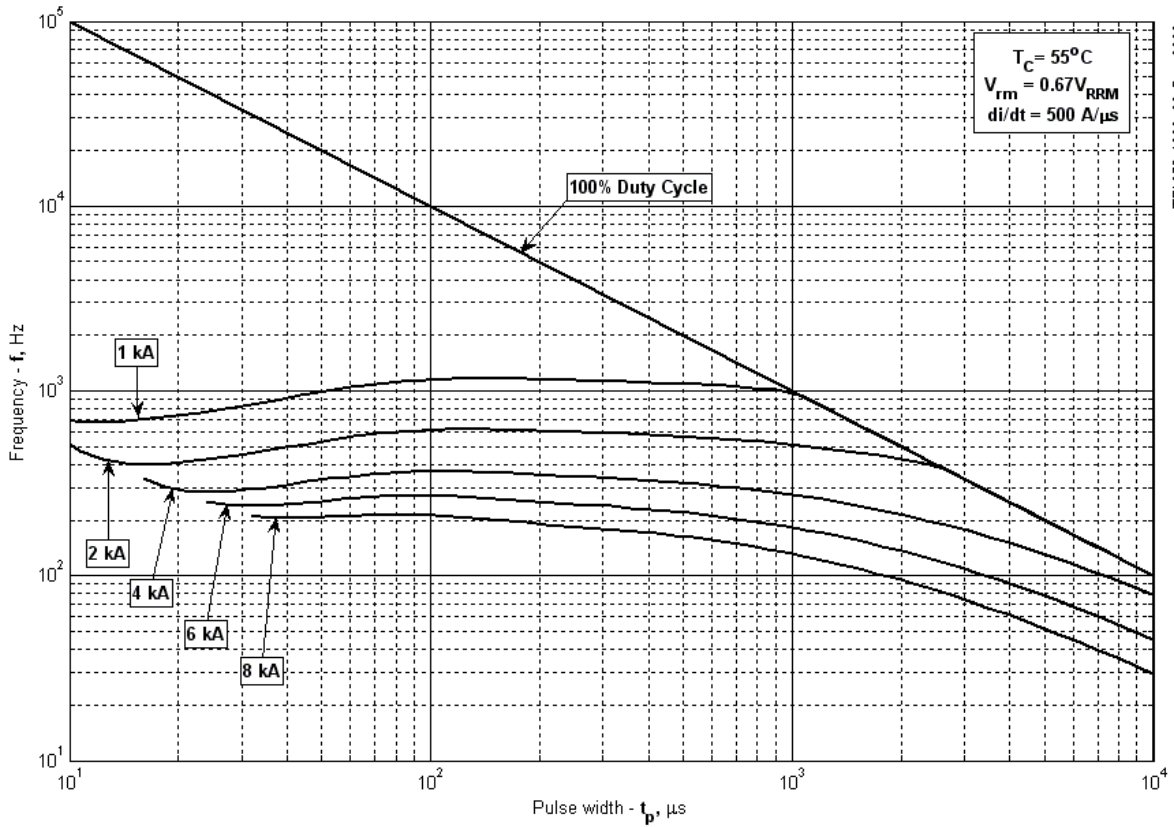
TFI873-1600, 06-Dec-2006

Fig 21 – Square wave energy per pulse



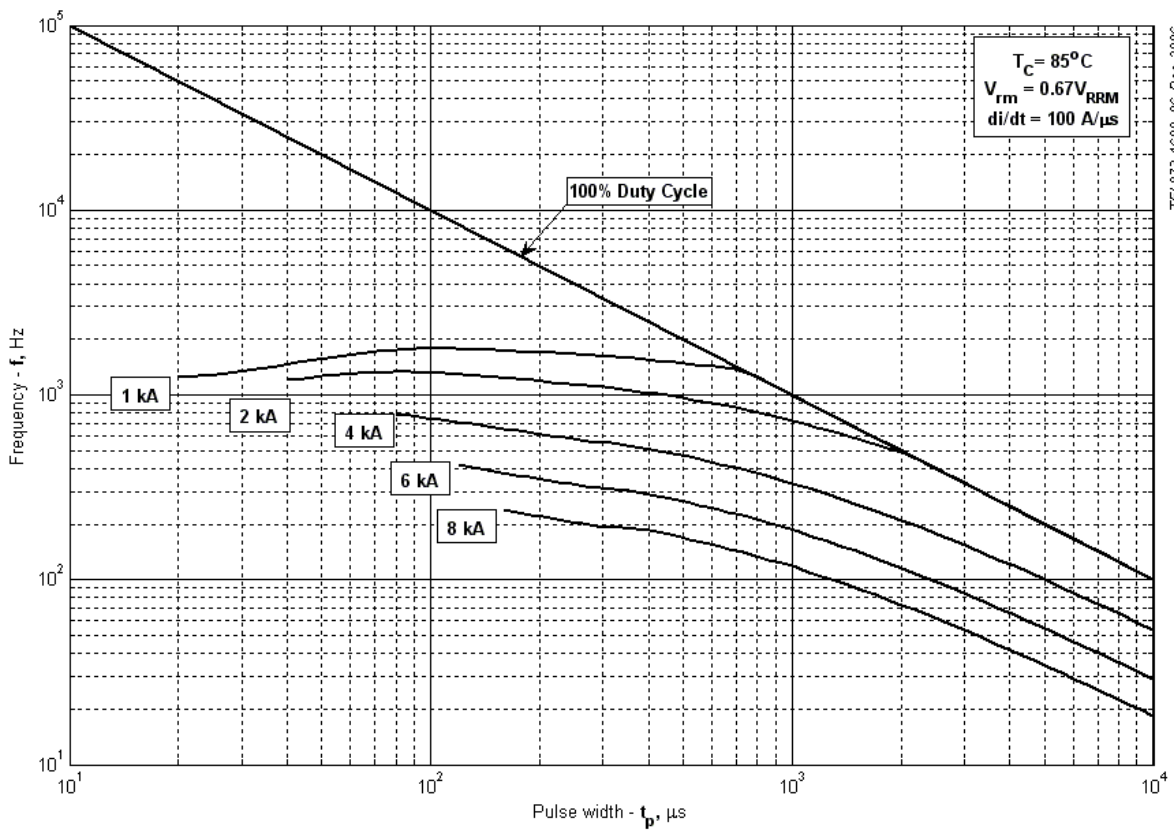
TFI873-1600, 06-Dec-2006

Fig 22 – Square wave frequency ratings



TFI873-1600, 06-Dec-2006

Fig 23 – Square wave frequency ratings



TFI 873-1600, 06-Dec-2006

Fig 24 – Square wave frequency ratings

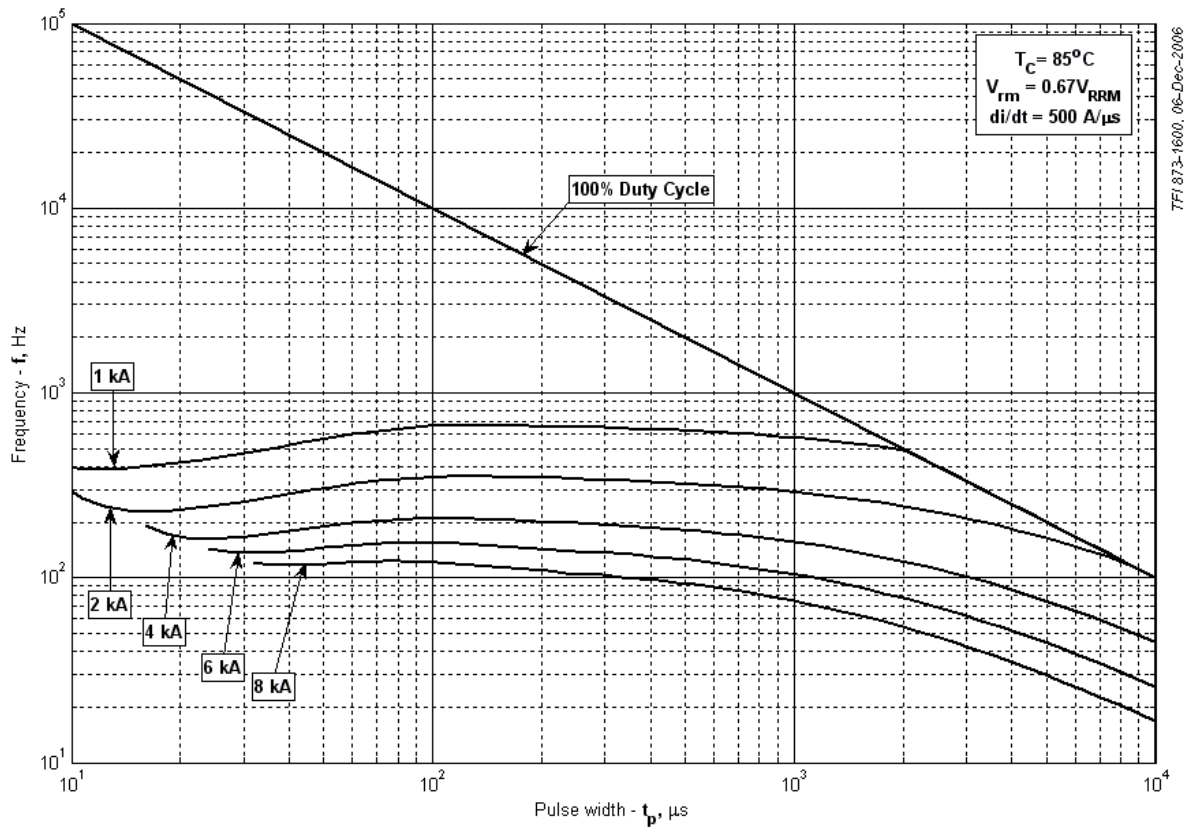


Fig 25 – Square wave frequency ratings

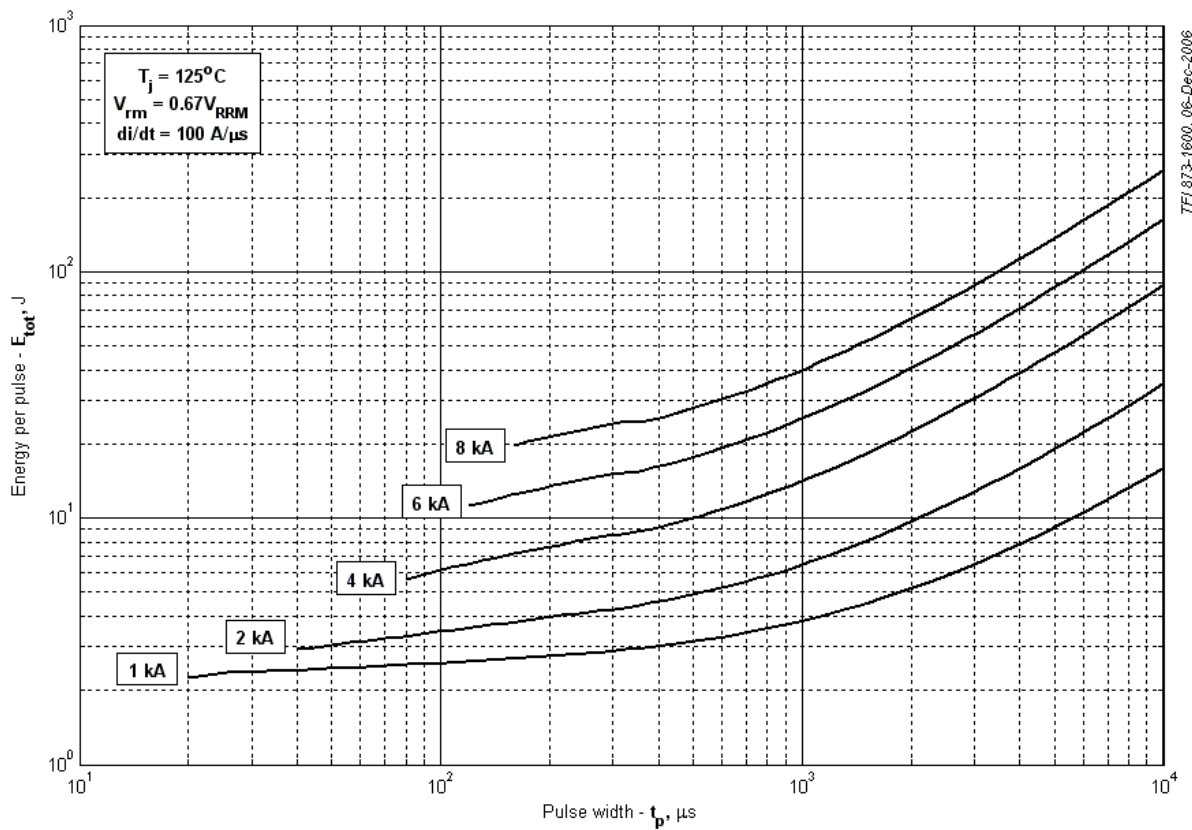


Fig 26 – Square wave energy per pulse

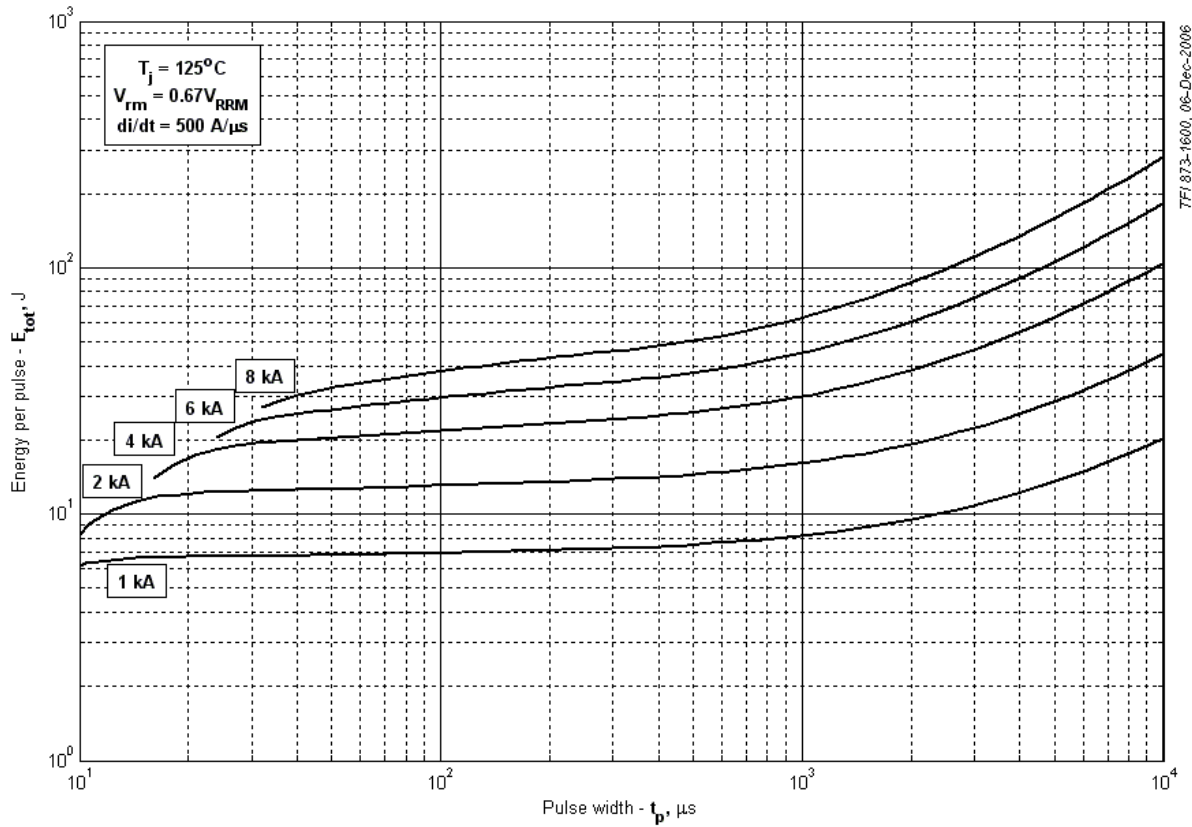


Fig 27 – Square wave energy per pulse

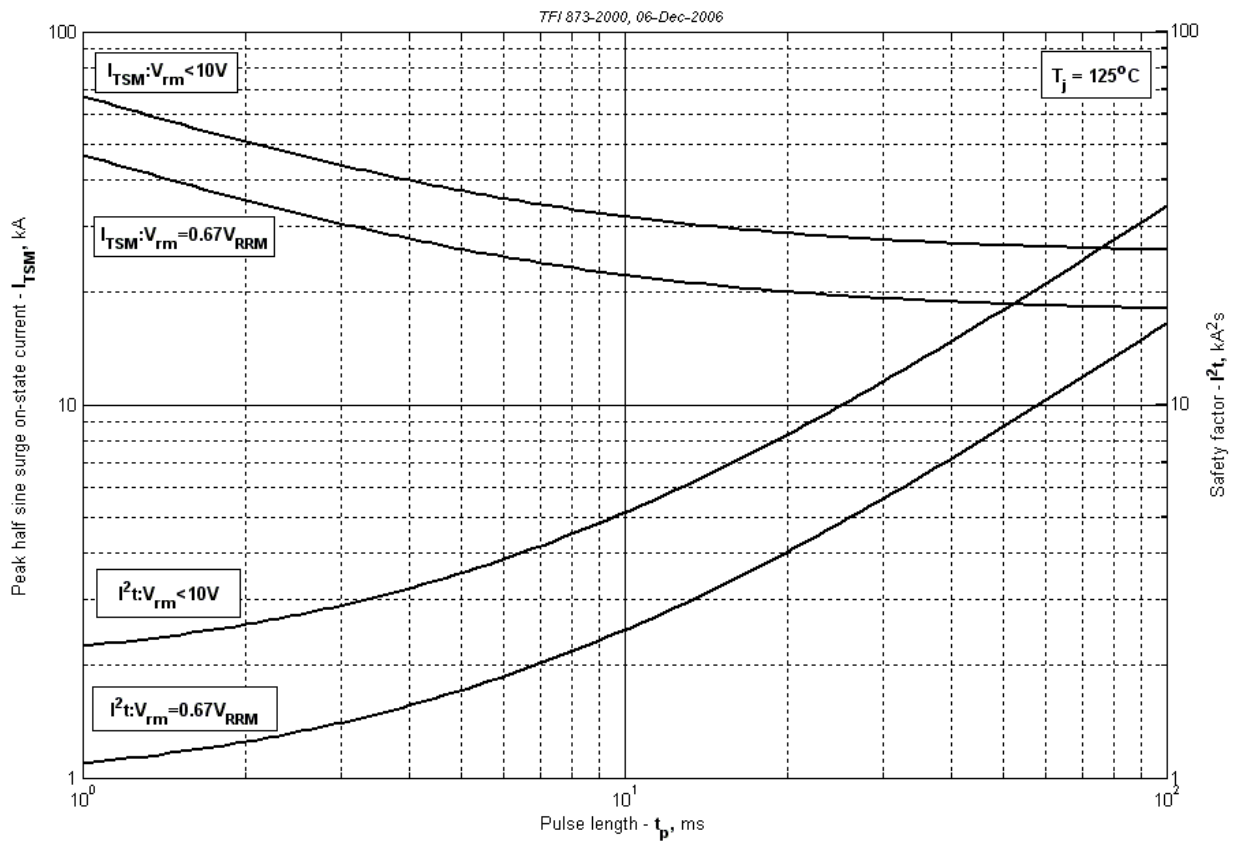


Fig 29 – Maximum surge and I^2t ratings

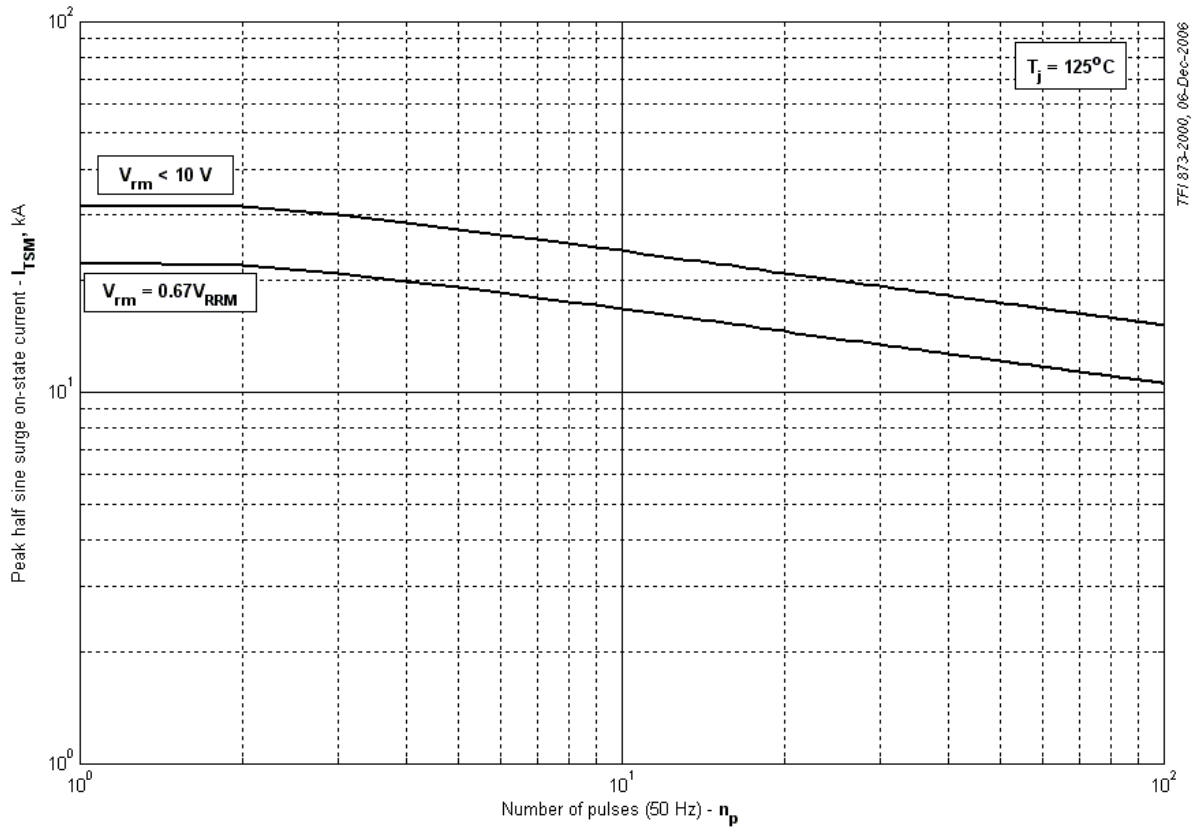


Fig 30 – Maximum surge ratings